# tehnotzka

https://tehnoteka.rs

## Informacije o proizvodu (EN)

HP računar 290 G4 (5W6H1EA)



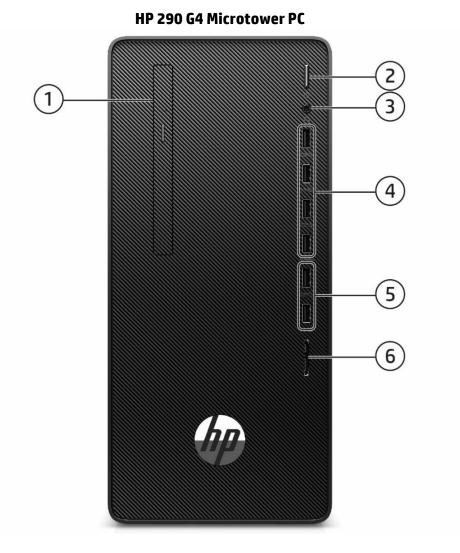


Tehnoteka je online destinacija za upoređivanje cena i karakteristika bele tehnike, potrošačke elektronike i IT uređaja kod trgovinskih lanaca i internet prodavnica u Srbiji. Naša stranica vam omogućava da istražite najnovije informacije, detaljne karakteristike i konkurentne cene proizvoda.

Posetite nas i uživajte u ekskluzivnom iskustvu pametne kupovine klikom na link:

https://tehnoteka.rs/p/hp-racunar-290-g4-5w6h1ea-akcija-cena/

## **Overview**



#### <u>Front</u>

- 1. Slim-height Bay supporting an optical disk drive (Optional)
- 2. Power Button
- 3. Combo jack, Headphone/ Microphone
- 4. (4) SuperSpeed USB 5Gbps port<sup>2</sup>
- 5. (2) SuperSpeed USB 10Gbps port<sup>2</sup>
- 6. SD Card Reader (Optional)

#### <u>Not Shown</u>

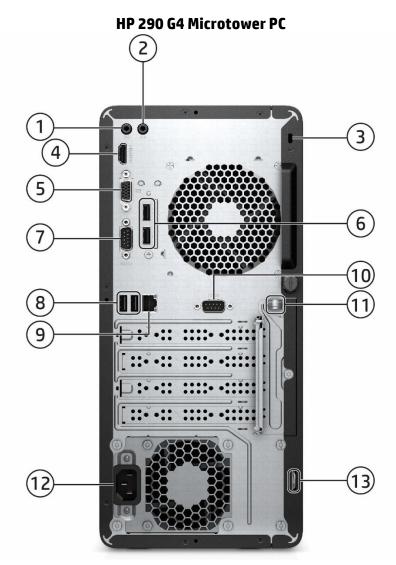
- Slots (1) PCI Express x16
  - (1) PCI Express x1
    - (1) PCI<sup>1</sup>
    - (1) M.2 for WLAN
    - (1) M.2 2242/2280 storage
- Bays (1) 3.5" or 2.5" internal HDD bay
  - (1) 3.5" or 2.5" internal HDD bay (share bay with caddy)
  - (1) 9.5mm internal optical drive bay

1. Available on select skus only.

2. SuperSpeed USB 10Gbps = USB 3.2 Gen2. SuperSpeed USB 5Gbps = USB 3.2 Gen1



## Standard Features and Configurable Modules



### <u>Back</u>

- 1. Audio Line out
- 2. Audio Line in
- 3. Standard lock slot
- 4. HDMI Port<sup>1</sup>
- 5. VGA Port<sup>1</sup>
- 6. Connector (2) USB 2.0 port (Optional)<sup>3</sup>

#### <u>Not Shown</u>

(1) PS/2 Port (Optional)

- (1) Parallel Port (Optional via PCIex1 slot),
- (1) 4 Serial Port (Optional via PCIex1 slot)<sup>2</sup>
- (1) Internal Speaker (Optional)
- (1) Intrusion Sensor (Optional)

- 7. Serial Port
- 8. Connector (2) USB 2.0 port
- 9. RJ-45 Network
- 10. Serial Port (Optional)
- 11. Integrated accessories cable lock
- 12. Power Cord Connector<sup>3</sup>
- 13. Padlock Loop

- 1. Port will be covered up when configured with processor which is without internal graphics.
- 2. Available in select countries only.
- 3. Power cord connector will be in different position, depends on which power supply configured.



## Standard Features and Configurable Modules

## AT A GLANCE

- Windows 10 Pro, Windows 10 Home or FreeDOS
- Intel<sup>®</sup> H470 chipset supporting Intel<sup>®</sup> 10<sup>th</sup> processors featuring Intel<sup>®</sup> UHD Graphics
- Supports an optional discrete graphics card
- Integrated 10/100/1000 Ethernet Controller or 802.11ac (1x1) Wi-Fi<sup>®</sup> and Bluetooth<sup>®</sup> 4.2 Combo
- Up to 64GB DDR4- 2933 Unbuffered Memory (UDIMM)
- Independent monitor support via VGA and HDMI interfaces
- TPM 2.0 support (either dTPM or fTPM) <sup>1</sup>
- Supports both Hard Disk Drives and M.2 PCIe NVMe Solid State Drives
- Up to 10 USB Ports (including native 4 SuperSpeed USB 5Gbps ports and 2 SuperSpeed USB 10Gbps<sup>3</sup> and 2 USB 2.0 ports)
- 180W/310W 90% HE power supply
- Security cable lock supported (sold separately)
- Intrusion sensor supported (Optional)
- Optional HP Care Services available; terms and conditions vary by country; certain restrictions and exclusions apply<sup>2</sup>

1. TPM feature will be supported on machine pre-configured with FreeDOS, and will be default set as enabled in BIOS setup menu if the machine is dTPM, but will be default set as disabled in BIOS setup menu if the machine is fTPM.

2. HP Care Services are optional. Service levels and response times for HP Care Services may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.

3. SuperSpeed USB 10Gbps = USB 3.2 Gen2. SuperSpeed USB 5Gbps = USB 3.2 Gen1

#### NOTE: See important legal disclosures for all listed specs in their respective features sections.

### **PRODUCT NAME**

HP 290 G4 Microtower PC

#### **OPERATING SYSTEM**

Preinstalled	Windows 11 Pro <sup>1</sup> Windows 11 Home - HP recommends Windows 11 Pro for business <sup>1</sup> Windows 10 Pro
Pre-installed (other)	Windows 10 Home - HP recommends Windows 11 Pro for business <sup>1,2</sup> FreeDOS
The instance (other)	

 Device comes with Windows 10 and a free Windows 11 upgrade or may be preloaded with Windows 11. Upgrade timing may vary by device. Features and app availability may vary by region. Certain features require specific hardware (see Windows 11 Specifications).
 Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows is automatically updated and enabled. High speed interneet and Microsoft account required. ISP fees apply and additional requirements may apply over time for updates.See http://www.windows.com.

#### PROCESSORS

#### Intel<sup>®</sup> Celeron<sup>®</sup> Processors<sup>2,3</sup>

CPU Intel Celeron G5900 Dual Core 3.4GHz 2666MHz 58W (3.4GHz, 2MB cache, 2 cores) CPU Intel Celeron G5905 Dual Core 3.4GHz 2666MHz 58W (3.4GHz, 2MB cache, 2 cores)

#### Intel<sup>®</sup> Pentium<sup>®</sup> Processors<sup>2,3</sup>

CPU Intel Pentium Gold G6400 Dual Core 4.0GHz 2666MHz 58W (4.0GHz, 4MB cache, 2 cores) CPU Intel Pentium Gold G6405 Dual Core 4.1GHz 2666MHz 58W (4.1GHz, 4MB cache, 2 cores) CPU Intel Pentium Gold G6600 Dual Core 4.2GHz 2666MHz 58W (4.2GHz, 4MB cache, 2 cores) CPU Intel Pentium Gold G6605 Dual Core 4.3GHz 2666MHz 65W (4.3GHz, 4MB cache, 2 cores)

#### **Intel 10th Processors**

#### Intel® Core™ i3<sup>2,3</sup>

CPU Intel Core i3-10100 4C 3.6GHz 2666MHz 65W (3.6GHz, turbo up to 4.3GHz, 6MB cache, 4 cores) CPU Intel Core i3-10105 4C 3.7GHz 2666MHz 65W (3.7GHz, turbo up to 4.4GHz, 6MB cache, 4 cores)

#### Intel<sup>®</sup> Core<sup>™</sup> i5<sup>2,3</sup>

CPU Intel Core i5-10400 6C 2.9GHz 2666MHz 65W (2.9GHz, turbo up to 4.3GHz, 12MB cache, 6 cores) CPU Intel Core i5-10500 6C 3.1GHz 2666MHz 65W (3.1GHz, turbo up to 4.5GHz, 12MB cache, 6 cores)

#### Intel<sup>®</sup> Core<sup>™</sup> i7<sup>2,3</sup>

CPU Intel Core i7-10700 8C 2.9GHz 2933MHz 65W (2.9GHz, Up to 4.8GHz with Intel® Turbo Boost<sup>4</sup>, 16MB cache, 8 cores)

2.Your product does not support Windows 8 or Windows 7, In accordance with Microsoft's support policy, HP does not support the Windows<sup>®</sup> 8 or Windows 7 operating system on products configured with Intel 8<sup>th</sup> or 9<sup>th</sup> generation and forward processors or provide any Windows<sup>®</sup> 8 or Windows 7 drivers on http://www.support.hp.com

3. Multi-Core is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. 64-bit computing system required. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance. 4. Intel® Turbo Boost technology requires a PC with a processor with Intel Turbo Boost capability. Intel Turbo Boost performance varies depending on hardware, software and overall system. See http://www.intel.com/technology/turboboost for more information \*NOTE: Only available on selected region

hp

## CHIPSET

Intel<sup>®</sup> H470 Chipset

#### GRAPHICS

#### Integrated<sup>5, 6</sup>

Intel<sup>®</sup> UHD Graphics 630 (integrated on 10<sup>th</sup> Core i processors and Pentium Gold G6600) Intel<sup>®</sup> UHD Graphics 610 (integrated on Pentium Gold G6400 and Celeron)

#### **Discrete Graphics**

AMD Radeon™ RX550X 4GB GFX AMD Radeon™ 520 1GB GFX NVIDIA® GeForce® GT730 2GB GFX NVIDIA® GeForce® GTX1660 Super 6GB GFX\*

5. HD content required to view HD images.

6. Integrated Intel software is available on select models only and requires separately purchased projector, tv or computer monitor with an integrated or external receiver. External receivers connect to the projector, tv or computer monitor via a standard VGA, HDMI cable, also sold separately.

**\*NOTE:** Available in select countries only

#### **MEMORY<sup>7</sup>**

Form Factor	Туре	Maximum	# of Slots
Microtower	DDR4 2933 (Transfer rates up	64 GB capacity	2 DIMM
	to 2933 MT/s) DDR4 2666 (Transfer rates up		
	to 2666 MT/s)		
4GB DDR4-2933 UDIMM NECC (1x4GB)			
8GB DDR4-2933 UDIMM NECC (1x8GB)			
8GB DDR4-2933 UDIMM NECC (2x4GB)			
16GB DDR4-2933 UDIMM NECC (2x8GB)			
16GB DDR4-2933 UDIMM NECC	(1x16GB)		
64GB DDR4-2933 UDIMM NECC (2x32GB)			
4GB DDR4-2666 UDIMM NECC (1x4GB)			
8GB DDR4-2666 UDIMM NECC (1x8GB)			
8GB DDR4-2666 UDIMM NECC (2x4GB)			
16GB DDR4-2666 UDIMM NECC (1x16GB)			
16GB DDR4-2666 UDIMM NECC	(2x8GB)		
64GB DDR4-2666 UDIMM NECC (2x32GB)			

7. Memory modules support data transfer rates up to 2933 MT/s; actual data rate is determined by the system's configured processor. See processor specifications for supported memory data rate. **NOTE:** DDR4-2933 UDIMM is only available for 10<sup>th</sup> Gen i7 processor.



Standard Features and Configurable Modules

### STORAGE

#### SATA3 - 3.5" or 2.5" 6Gb/s HDDs

2TB 7200 RPM SATA Hard Disk Drive 1TB 7200 RPM SATA Hard Disk Drive 500GB 7200 RPM SATA Hard Disk Drive

#### **Solid State Drives**

128GB M.2 NVMe 256GB M.2 NVMe 512GB M.2 NVMe

SD Card Reader<sup>8</sup> SD/SDHC/SDXC SD Card Reader

## Intel Optane Memory<sup>8</sup>

SSD Intel 16GB 2280 Optane Memory

#### 8. Optional per configuration

#### **OPTICAL DISC DRIVES**

DVD-ROM 9.5mm

DVD-Writer<sup>9</sup> 9.5mm

9. HD-DVD disks cannot be played on this drive. No support for DVD-RAM. Actual speeds may vary. Don't copy copyright-protected materials. Double Layer discs can store more data than single layer discs. Discs burned with this drive may not be compatible with many existing single-layer DVD drives and players.

#### **NETWORKING<sup>10</sup>**

## Ethernet (RJ-45)

Integrated 10/100/1000M GbE LAN

#### Wi-Fi<sup>®</sup> and Bluetooth<sup>®</sup>

802.11ac (1x1) Wi-Fi<sup>®</sup> and Bluetooth<sup>®</sup> 4.2 Combo

10. Wireless cards are optional or add-on features and requires separately purchased wireless access point and internet service. Availability of public wireless access points limited.



## Standard Features and Configurable Modules

## AUDIO / MULTIMEDIA

Realtek ALC3601 / ALC3867-CG Integrated Hi-Definition Audio Combo Jack, Headphone / Microphone Line-in / Line-out (3.5mm)

### **KEYBOARDS AND POINTING DEVICES<sup>11</sup>**

#### Keyboard

USB Business Slim Wired Keyboard HP USB Wired Keyboard Business Slim USB Antimicrobial Wired Keyboard (China) Business Slim PS/2 Wired Keyboard (for machine configured with PS/2 port) No KB Option

#### Mouse

Antimicrobial USB Mouse (China) HP Optical USB Mouse Universal Wired USB Mouse USB Hardened Mouse (Specific region) HP PS/2 Mouse (for machine configured with PS/2 port) No Mouse Option

11. Keyboards and mouse are optional or add-on features.

### PORTS

#### Front

Slim-height Bay - supporting an optical disk drive (Optional) Power Button Combo jack, Headphone / Microphone SD Card Reader (Optional) (2) SuperSpeed USB 10Gbps port\*\* (4) SuperSpeed USB 5Gbps port\*\*

#### Not Shown

(1) PCI Express x16
 (1) PCI Express x1
 (1) Full-height PCI (Available on selected sku)
 (1) M.2 for WLAN
 (1) M.2 2242/2280 storage

#### Rear

Audio Line out



Audio Line in HDMI Port VGA Port Serial Port (Optional on selected sku) 2<sup>nd</sup> Serial Port (Optional) Standard Lock Slot (2) USB 2.0 port (2) USB 2.0 port (Optional on selected sku) RJ-45 Network connector Power cord connector Padlock loop Integrated accessories cable lock

#### Not Shown

(1) PS/2 Port (Optional)
 (1) Parallel Port (Optional via PCIex1 slot)
 (1) 4x Serial port (Optional via PCIex1 slot)\*
 (1) Internal Speaker (Optional)
 (1) Intrusion Sensor (Optional)

**NOTE\*:** Available in select countries only. **NOTE\*\*:** SuperSpeed USB 10Gbps = USB 3.2 Gen2. SuperSpeed USB 5Gbps = USB 3.2 Gen1

### BAYS

- (1) 9.5mm external slimline ODD bay (Optional)
- (1) 3.5" or 2.5" internal HDD or bay
- (1) 3.5 or 2.5" internal HDD bay (share bay with caddy)

### SOFTWARE COMPONENTS AND APPLICATIONS WITH WINDOWS

Security and Protection McAfee\* LiveSafe<sup>™ 12</sup>

#### Productivity

Buy Office (sold separately) Dropbox<sup>13</sup> Xerox<sup>®</sup> DocuShare<sup>®</sup> (90 days free trial offer)<sup>16</sup>

#### **ODD Playback**

sMedio True DVD for HP

Movies

Netflix<sup>14</sup>

App Stores and Content Purchasing Amazon<sup>14</sup>

#### **HP Utilities and Support**

HP Documentation HP JumpStarts HP Audio Switch<sup>15</sup> HP Support Assistant

#### BTB

HP Setup Integrated OOBE

#### Hardware Enabling Drivers or software utility

HP System Event Utility

12. Free 1-year subscription of McAfee LiveSafe service included. Internet access required and not included. Subscription required after expiration 13. New Dropbox users are eligible to get 25 GB of Dropbox space free for 12 months from date of registration. For complete details and terms of use, including cancellation policies, visit the Dropbox website at https://www.dropbox.com/help/space/hp-promotion. Internet service required and not included.

14. Internet access required and not included.

15. Easily switch between speaker and microphone sources with intuitive controls and a consistent app experience.

16. Simply sign up and start using Xerox<sup>®</sup> DocuShare<sup>®</sup> Go. No credit card. No obligation. Data will become unavailable unless a subscription is entered before the end of the 90 days free trial period. See visit https://http://www.xerox.com/docusharego for details. \*NOTE: Available in Latin America countries only.

#### **POWER SUPPLY<sup>17</sup>**

180 W ENERGY® STAR® Libra2 EPA90 (Gold) Full range 115V/230V 310 W SFF ENTL EPA90 (Gold) Full range 115V/230V 500 W EPA90 (Gold) Full range 115V/230V

17. All power supplies are not available in every region.



Standard Features and Configurable Modules

### **DIMENSIONS AND WEIGHT**

#### Dimensions

6.12 x 11.93 x 13.28 in (155 x 303 x 337 mm)

#### Weight

10.4 lbs / 4.7 kg

### UNIT ENVIRONMENT AND OPERATING CONDITIONS

#### **General Unit Operating Guidelines**

- Keep the computer away from excessive moisture, direct moisture and the extremes of heat and cold, to ensure that unit is operated within the specified operating range.
- Leave a 10.2 cm (4 in) clearance on all vented sides of the computer to permit the required airflow.
- Never restrict airflow into the computer by blocking any vents or air intakes.
- Do not stack computers on top of each other or place computers so near each other that they are subject to each other's re-circulated or preheated air.
- Occasionally clean the air vents on the front, back, and any other vented side of the computer. Lint, dust and other foreign
  matter can block the vents and limit the airflow.
- If the computer is to be operated within a separate enclosure, intake and exhaust ventilation must be provided on the
  enclosure, and the same operating guidelines listed above will still apply.

Temperature Range	Operating: 5° to 35° C <sup>18</sup> Non-operating: -30° to 60° C <sup>18</sup>
Relative Humidity	Operating: 5% to 90% (non-condensing at ambient) Non-operating: 5% to 90% (non-condensing at ambient)
Maximum Altitude (unpressurized)	Operating: 5000 m Non-operating: 50000ft (15240 m)

18. Operating temperature is de-rated 1.0 deg C per 300 m (1000 ft) to 3000 m (10,000 ft) above sea level, no direct sustained sunlight. Maximum rate of change is 10 deg C/Hr. The upper limit may be limited by the type and number of options installed.

Eco-Label Certifications & declarations	<ul> <li>This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks: <ul> <li>IT ECO declaration</li> <li>US ENERGY STAR<sup>®</sup></li> <li>US Federal Energy Management Program (FEMP)</li> <li>EPEAT<sup>D</sup> Gold registered in the United States. See http://www.epeat.net for registration status in your country.</li> <li>TCO Certified</li> <li>China Energy Conservation Program (CECP)</li> <li>China State Environmental Protection Administration (SEPA)</li> <li>Taiwan Green Mark</li> <li>Korea Eco-label</li> <li>Japan PC Green label</li> </ul> </li> </ul>
	Commission Regulation (EC) No 617/2013 (ErP Lot 3)
System Configuration	The configuration used for the Energy Consumption and Declared Noise Emissions data for the Desktop model is based on a "Typically Configured Desktop".



Energy Consumption (in accordance with US ENERGY STAR® test method)	115VAC, 60Hz	230VAC	, 50Hz	100VAC, 50Hz	
Normal Operation (Short idle)	35.98W	35.98W 36.76		36.52W	
Normal Operation (Long idle)	33.27W	33.0	3W	33.26W	
Sleep	1.08W	1.1	N	1.27W	
Off	0.27W	0.3	N	0.26W	
	<b>NOTE:</b> Energy efficiency data listed is f family. HP computers marked with the Environmental Protection Agency (EPA offer ENERGY STAR® compliant configu featuring a hard disk drive, a high effic	ENERGY STAR <sup>®</sup> Logo ) ENERGY STAR <sup>®</sup> spe urations, then energy	o are compliant wit cifications for com / efficiency data lis	th the applicable U.S. Iputers. If a model family does not Ited is for a typically configured PC	
Heat Dissipation*	115VAC, 60Hz	230VAC	, 50Hz	100VAC, 50Hz	
Normal Operation (Short idle)	122.69 BTU/hr	125.35 E	BTU/hr	124.53 BTU/hr	
Normal Operation (Long idle)	113.45 BTU/hr	112.63 E	BTU/hr	113.42 BTU/hr	
Sleep	3.68 BTU/hr	3.75 B1		4.33 BTU/hr	
Off	0.92 BTU/hr	1.02 BT	TU/hr	0.89 BTU/hr	
	<b>NOTE:</b> Heat dissipation is calculated based on the measured watts, assuming the service level is attained hour.		the service level is attained for one		
Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)			Sound Pressure (L <sub>pAm</sub> , decibels)		
Typically Configured – Idle	3.7			24.7	
Fixed Disk – Random writes	4		29.8		
Longevity and Upgrading	This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include: Spare parts are available throughout the warranty period and or for up to "3" years after the end of production.				
Batteries	This battery(s) in this product comply with EU Directive 2006/66/EC Batteries used in the product do not contain: Mercury greater the1ppm by weight Cadmium greater than 20ppm by weight Battery size: CR2032 (coin cell) Battery type: Lithium				
Additional Information       • This product is in compliance with the Restrictions of Hazardous Substance 2011/65/EC.         • This HP product is designed to comply with the Waste Electrical and Electre Directive – 2002/96/EC.         • This product is in compliance with California Proposition 65 (State of California and Toxic Enforcement Act of 1986).         • This product is in compliance with the IEEE 1680.1 (EPEAT) standard at the http://www.epeat.net.         • Plastics parts weighing over 25 grams used in the product are marked per		Electronic Equipment (WEEE) f California; Safe Drinking Water at the <silver> level, see</silver>			



Not all configuration components are available in all regions/countries. c06590421 — DA 16653 — EMEA — Version 16 — February 2, 2023

ernal: ernal: s product of HP Genera p://www.h sbestos ertain Azo ertain Bror admium hlorinated hlorinated prmaldehy alogenated ead carbon ead and Le ercuric Ox	PAPER/Paperboard PAPER/Molded Pul PLASTIC/Polyethyl does not contain any al Specification for th p.com/hpinfo/globa Colorants ninated Flame Retar Hydrocarbons Paraffins de d Diphenyl Methanes ates and sulfates ad compounds	p ene low density - LD of the following sub ne Environment at lcitizenship/environ dants – may not be u	PE ostances in excess ment/pdf/gse.pdf	1220 g 520 g 53 g 5 of regulatory limits (refer to f):
ernal: s product of HP Genera p://www.h sbestos ertain Azo ertain Bror admium hlorinated hlorinated plorinated prmaldehy alogenated ead carbon ead and Le ercuric Ox	PAPER/Molded Pul PLASTIC/Polyethyl does not contain any al Specification for th p.com/hpinfo/globa Colorants ninated Flame Retar Hydrocarbons Paraffins de d Diphenyl Methanes ates and sulfates ad compounds	p ene low density - LD of the following sub ne Environment at lcitizenship/environ dants – may not be u	ostances in excess ment/pdf/gse.pdf	520 g 53 g 5 of regulatory limits (refer to f):
s product of HP Genera p://www.h sbestos ertain Azo ertain Bror admium nlorinated nlorinated plorin	PLASTIC/Polyethyl does not contain any al Specification for th p.com/hpinfo/globa Colorants ninated Flame Retar Hydrocarbons Paraffins de d Diphenyl Methanes ates and sulfates ad compounds	ene low density - LD of the following sub ne Environment at lcitizenship/environi dants – may not be u	ostances in excess ment/pdf/gse.pdf	53 g 5 of regulatory limits (refer to f):
HP Genera p://www.h sbestos ertain Azo ertain Bror admium hlorinated hlorinated prmaldehy alogenated ead carbon ead and Le ercuric Ox	loes not contain any al Specification for th p.com/hpinfo/globa Colorants ninated Flame Retar Hydrocarbons Paraffins de d Diphenyl Methanes ates and sulfates ad compounds	of the following sub ne Environment at lcitizenship/environ dants – may not be u	ostances in excess ment/pdf/gse.pdf	s of regulatory limits (refer to f):
HP Genera p://www.h sbestos ertain Azo ertain Bror admium hlorinated hlorinated prmaldehy alogenated ead carbon ead and Le ercuric Ox	al Specification for th p.com/hpinfo/globa Colorants ninated Flame Retar Hydrocarbons Paraffins de d Diphenyl Methanes ates and sulfates ad compounds	ne Environment at Icitizenship/environi dants – may not be u	ment/pdf/gse.pdf	f):
This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf): • Asbestos • Certain Azo Colorants • Certain Brominated Flame Retardants – may not be used as flame retardants in plastics • Cadmium • Chlorinated Hydrocarbons • Chlorinated Paraffins • Formaldehyde • Halogenated Diphenyl Methanes • Lead carbonates and sulfates • Lead and Lead compounds • Mercuric Oxide Batteries • Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user. • Ozone Depleting Substances • Polybrominated Biphenyls (PBBs) • Polybrominated Biphenyl Ethers (PBBEs) • Polybrominated Biphenyl (PCB) • Polybrominated Biphenyl (PCB) • Polychlorinated Terphenyls (PCT) • Polychlorinated Terphenyls (PCT) • Polychlorinated Terphenyls (PCT) • Polychlorinated Form most applications. • Radioactive Substances • Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)				
iminate th terials. iminate th esign pack aximize th se readily p educe size astic pack Inc. offers ycle your p es office. F nner. EU WEEE th product osted on t y be used p egrate and bal Citizen p://www.h	e use of heavy meta e use of ozone-deple aging materials for e e use of post-consu recyclable packaging and weight of packa aging materials are n end-of-life HP produ product, please go to products returned to directive (2002/95/R type for use by treat he Hewlett Packard py recyclers and othe re-sell HP equipmer ship Report p.com/hpinfo/globa	ls such as lead, chron eting substances (OE ease of disassembly. mer recycled content materials such as p iges to improve trans <u>marked according to</u> uct return and recycl : http://www.hp.con HP will be recycled, n EC) requires manufac ment facilities. This web site at: http://w er WEEE treatment fa nt.	mium, mercury an DS) in packaging m t materials in pack aper and corruga sportation fuel ef <u>ISO 11469 and D</u> ing programs in m n/go/reuse-recyc recovered or disp cturers to provide information (proc ww.hp.com/go/re acilities as well as	nd cadmium in packaging naterials. kaging materials. ted materials. ficiency. IN 6120 standards. nany geographic areas. To le or contact your nearest HP osed of in a responsible treatment information for duct disassembly instructions) ecyclers. These instructions
rizololololuariifi ire a seelalryen ethoyed	ied by the one Deple lybromina lybromina lybromina lychlorina lychlorina lychlorina lychlorina lychlorina lyvinyl Ch ntarily re dioactive <u>butyl Tin</u> ollows the minate th erials. minate th eri	ied by the user. one Depleting Substances lybrominated Biphenyls (PBBs lybrominated Biphenyl Ethers lybrominated Biphenyl Oxides lychlorinated Biphenyl (PCB) lychlorinated Terphenyls (PCT lyvinyl Chloride (PVC) – excep ntarily removed from most ap dioactive Substances <u>butyl Tin (TBT), Triphenyl Tin</u> ollows these guidelines to dee minate the use of heavy meta erials. minate the use of ozone-deple sign packaging materials for eximize the use of post-consule e readily recyclable packaging duce size and weight of packa astic packaging materials are in nc. offers end-of-life HP product cle your product, please go to s office. Products returned to ner. EU WEEE directive (2002/95/K n product type for use by treat osted on the Hewlett Packard is bated on the Hewlett Packard is bate certifications	ied by the user. one Depleting Substances lybrominated Biphenyls (PBBs) lybrominated Biphenyl Ethers (PBBEs) lybrominated Biphenyl (PCB) lychlorinated Terphenyls (PCT) lyvinyl Chloride (PVC) – except for wires and cables ntarily removed from most applications. dioactive Substances butyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin 02 ollows these guidelines to decrease the environme minate the use of heavy metals such as lead, chrone erials. minate the use of ozone-depleting substances (OE sign packaging materials for ease of disassembly. eximize the use of post-consumer recycled content e readily recyclable packaging materials such as p duce size and weight of packages to improve trans astic packaging materials are marked according to nc. offers end-of-life HP product return and recycl cle your product, please go to: http://www.hp.com s office. Products returned to HP will be recycled, mer. EU WEEE directive (2002/95/EC) requires manufact ner offers and other WEEE treatment fac grate and re-sell HP equipment. bal Citizenship Report ://www.hp.com/hpinfo/globalcitizenship/gcrepor label certifications	ied by the user. one Depleting Substances lybrominated Biphenyls (PBBs) lybrominated Biphenyl Oxides (PBBCs) lybrominated Biphenyl Oxides (PBBOs) lychlorinated Biphenyl (PCB) lychlorinated Terphenyls (PCT) lyvinyl Chloride (PVC) – except for wires and cables, and certain retain rtarily removed from most applications. dioactive Substances butyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO) ollows these guidelines to decrease the environmental impact of pr minate the use of heavy metals such as lead, chromium, mercury ar erials. minate the use of ozone-depleting substances (ODS) in packaging r sign packaging materials for ease of disassembly. iximize the use of post-consumer recycled content materials in pace e readily recyclable packaging materials such as paper and corruga duce size and weight of packages to improve transportation fuel ef <u>istic packaging materials are marked according to ISO 11469 and D</u> nc. offers end-of-life HP product return and recycling programs in r cle your product, please go to: http://www.hp.com/go/reuse-recyc s office. Products returned to HP will be recycled, recovered or disp ner. EU WEEE directive (2002/95/EC) requires manufacturers to provide a product type for use by treatment facilities. This information (pro- psted on the Hewlett Packard web site at: http://www.hp.com/go/re be used by recyclers and other WEEE treatment facilities as well as grate and re-sell HP equipment. val Citizenship Report ://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html



ISO 14001 certificates:
http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_ISO_14K_
Certificate.pdf
and
http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf

#### **SERVICE AND SUPPORT**

On-site Warranty 1: Available three-year (3-3-3) or one-year (1-1-1) limited warranty (varies by country) delivers on-site, next business day 2 service for parts and labor and complimentary limited technical support.3 Three-year onsite and labor are not available in all countries. Service offers terms up to 5 years by choosing an optional HP Care Pack.4 To choose the right level of service for your HP product, visit HP Care Pack Central: http://www.hp.com/go/cpc.

**NOTE 1:** Terms and conditions may vary by country. Certain restrictions and exclusions apply. Other warranty variations may be offered in your region.

**NOTE 2:** On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country. **NOTE 3:** Technical support applies only to HP-configured and third-party HP qualified hardware and software.

**NOTE 4:** Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit <a href="http://www.hp.com/go/cpc">http://www.hp.com/go/cpc</a>. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.



## Technical Specifications - Graphics

## GRAPHICS

•	ntegrated on Core i7/i5/i3/Pentium G6500 and above processors) Itegrated on Pentium G6400 and below/ and Celeron)	
DisplayPort™	Multimode capable; supports HDCP, DisplayPort™ Audio (2 streams), HBR2 link rates and Multi-Stream Technology for a maximum of 3 displays (including the integrated panel)	
Memory	Additional memory is allocated for graphics as needed using Intel's Dynamic Video Memory Technology (DVMT), to provide an optimal balance between graphics and system memory use.	
Maximum Graphics Memory	Windows 10: >4 GB	
Maximum Color Depth	32 bits/pixel	
Graphics/Video API Support	10 <sup>th</sup> Generation Intel <sup>®</sup> Core Processors, Pentium and Celeron	
	With Intel® UHD Graphics 630	
	Pentium <sup>®</sup> and Celeron <sup>®</sup>	
	With Intel <sup>®</sup> UHD Graphics 610	
Supported Display Resolutions	Max. Resolution (VGA) 2048 x 1536@60Hz	
and Refresh Rates	Max. Resolution (HDMI) 4096 x 2160@60Hz	
configuration. <b>Note:</b> other resolutions may be available	n graphics memory can be less than the amounts listed above depending upon your computer's able but are not recommended as they may not have been tested and qualified by HP	

Only supported on displays connected to the external DisplayPort<sup>™</sup> connector.



## Technical Specifications - Graphics

### AMD Radeon™ R7 430 2GB Graphics Card

Engine Clock	780 MHz
Memory Clock	1100 MHz
Memory Size(width)	2GB(64-bit)
Memory Type	256M x 32 GDDR5
Max. Resolution(VGA)	2048x1536
Max. Resolution(DP)	4096x2160@60Hz
Multi Display Support	2 displays
HDCP Compliance	yes
Rear I/O connectors(bracket)	VGA+DP
Cooling(active/passive)	Active fan-sink (Active cooling with dynamic speed)
Total power consumption(W)	<50W
PCB form-factor with bracket	LP PCB with FH/LP bracket

#### AMD<sup>®</sup> Radeon<sup>™</sup> RX550X 4 GB FH PCIe x16

Engine Clock	1183MHz
Memory Clock	6 Gbps
Memory Size(width)	4 GB(128-bit)
Memory Type	GDDR5
Max. Resolution(HDMI)	4096x2160 @ 60Hz
Max. Resolution(DP)	5120x2880 @ 60Hz
Multi Display Support	2 displays
HDCP Compliance	Yes
Rear I/O connectors(bracket)	HDMI, DPx2
Cooling(active/passive)	Active fan-sink (Active cooling with dynamic speed)
Total power consumption(W)	<50W
PCB form-factor with bracket	LP (low profile) PCB with FH/LP bracket

### AMD Radeon™ 520 1GB Graphics Card

(hp

780 MHz
1100 MHz
1GB(32-bit)
256M x 32 GDDR5
2048x1536
4096x2160@60Hz
2 displays
yes
VGA+DP
Active fan-sink (Active cooling with dynamic speed)
<50W
LP PCB with FH/LP bracket



## Technical Specifications - Graphics

## NVIDIA® GeForce® GTX 1660 Super 6GB Graphics Card

Engine Clock	1785 MHz
Memory Clock	7000 MHz
Memory Size(width)	6GB(192-bit)
Memory Type	256M x 32 GDDR6 @6pcs
Max. Resolution(DVI)	7680x4320@120Hz
Max. Resolution(DP)	7680x4320@120Hz
Multi Display Support	3 displays
HDCP Compliance	yes
Rear I/O connectors(bracket)	DVI-D+DP+HDMI
Cooling(active/passive)	Active fan-sink(Active cooling with dynamic speed)
Total power consumption(W)	<125W
PCB form-factor with bracket	FH PCB with FH bracket

Technical Specifications - Storage

### STORAGE\*

### HP 2 TB 7.2K rpm SATA 6.0Gb/s 3.5" Hard Disk Drive

Capacity	2 TB
Rotational Speed	7,200 rpm
Interface	SATA 6Gb/s NCQ
Buffer Size	64 MB
Logical Blocks	3,907,029,168
Seek Time	Read: <8.5 ms Write: <9.5 ms
Height	1.028 in/26.11 mm
Width	4.0 in/101.6 mm
Operating Temperature	32° to 140° F (0° to 60° C)

## 1 TB 7.2K rpm SATA 6.0Gb/s 3.5" Hard Disk Drive

Capacity	1 TB
Rotational Speed	7,200 rpm
Interface	Serial ATA 3.0 (6.0 Gb/s)
Buffer Size	32 MB
Logical Blocks	1,953,525,168
Seek Time	Single Track: 2.0 ms Average: 11 ms Full-Stroke: 21 ms
Height	1 in/2.54 cm
Width	Media diameter: 3.5 in/8.89 cm Physical size: 4 in/10.2 cm
Operating Temperature	41° to 131° F (5° to 55° C)

## 500 GB 7.2K rpm SATA 6.0Gb/s 3.5" Hard Disk Drive

Capacity Rotational Speed Interface Buffer Size	500 GB 7,200 rpm Serial ATA 3.0 (6.0 Gb/s) 32 MB
Logical Blocks Seek Time	1,953,525,168 Single Track: 2.0 ms Average: 11 ms Full-Stroke: 21 ms
Height Width	1 in/2.54 cm Media diameter: 3.5 in/8.89 cm Physical size: 4 in/10.2 cm
Operating Temperature	41° to 131° F (5° to 55° C)



Technical Specifications - Storage

### 128 GB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight	< 10g
Capacity	128GB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIE Gen3x4
Maximum Sequential Read	Up to 2800MB/s
Maximum Sequential Write	Up to 600MB/s
Logical Blocks	250,069,680
Operating Temperature Features	0° to 70°C (32° to 158°F) [ambient temp] APST; ASPM L1.2; NVME spec 1.2

### 256 GB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight	< 10g
Capacity	256GB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIE Gen3x4
Maximum Sequential Read	Up to 2700MB/s
Maximum Sequential Write	Up to 1000MB/s
Logical Blocks	500,118,192
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	APST; ASPM L1.2; NVME spec 1.2

### 512 GB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight	< 10g
Capacity	512GB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIE Gen3x4
Maximum Sequential Read	Up to 2900MB/s
Maximum Sequential Write	Up to 1100MB/s
Logical Blocks	1,000,215,216

## Technical Specifications - Storage

Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	APST; ASPM L1.2; NVME spec 1.2

#### 256 GB M.2 2280 PCIe NVMe SSD

Drive Weight	< 10g
Capacity	256 GB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIE Gen3
Maximum Sequential Read	Up to 1600MB/s
Maximum Sequential Write	Up to 780MB/s
Logical Blocks	500,118,192
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	APST; ASPM L1.2; NVME spec 1.2

### 512 GB M.2 2280 PCIe NVMe SSD

Drive Weight	< 10g
Capacity	512 GB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIE Gen3
Maximum Sequential Read	Up to 1600MB/s
Maximum Sequential Write	Up to 860MB/s
Logical Blocks	1,000,215,216
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	APST; ASPM L1.2; NVME spec 1.2

#### 500 GB 7200RPM 2.5in SATA HDD

Capacity	500 GB
Rotational Speed	7,200 rpm
Interface	SATA 6 Gb/s
Buffer Size	32 MB
Logical Blocks	976,773,168
Seek Time	12 ms (Average)
Height	0.267 in/6.8 mm (nominal)
Width (nominal)	2.75 in/70 mm (nominal)



Technical Specifications - Storage

**Operating Temperature** 41° to 131° F (5° to 55° C)

#### 1TB 7200RPM 2.5in SATA HDD

Capacity	1 TB
Rotational Speed	7,200 rpm
Interface	SATA 6 Gb/s
Buffer Size	32 MB
Logical Blocks	1,953,525,168
Seek Time	12 ms (Average)
Height	0.374 in/9.5 mm (nominal)
Width (nominal)	2.75 in/70 mm (nominal)
Operating Temperature	41° to 131° F (5° to 55° C)

Technical Specifications – Optical Drives

### **OPTICAL DISC DRIVES**

### HP 9.5mm Desktop G2 Slim DVD Writer Drive

Height	9.5 mm height		
Orientation	Either horizontal or vertical		
Interface type	SATA/ATAPI		
Disc recording capacity	Up to 8.5 GB DL or 4.7 GB standard		
Dimensions (W x H x D)	5.04 x 0.37 x 5.0 in (128 x 9.5 x 127 mm) without bezel		
Weight (max)	0.31 lb (140 g)		
Read Speeds	DVD-R DL DVD+R DVD+RW DVD+R DL DVD-R DVD-RW CD-R CD-RW DVD-RW, DVD+RW DVD-RW, DVD+R DL DVD-R DL, DVD+R DL DVD+R, DVD-R DVD-ROM DL, DVD-ROM CD-ROM, CD-R CD-RW	Up to 6X Up to 8X Up to 8X Up to 6X Up to 8X Up to 6X Up to 24X Up to 10X Up to 8X Up to 8X Up to 8X Up to 8X Up to 8X Up to 8X Up to 24X Up to 24X	
Access time (typical reads, including settling)	Random DVD-ROM: 170 ms (typical), CD-ROM: 170 ms (typical) Full Stroke DVD-ROM: 320 ms (typical), CD-ROM: 320 ms (typical) Stop Time 6 seconds (typical)		
Power	Source Slimline SATA DC power receptacle DC Power Requirement 5 VDC ± 5%-100 mV ripple p-p DC Current 5 VDC (< 1000 mA typical, 1600 mA maximum)		
Environmental conditions (operating - non-condensing)	Temperature 41° to 122° F (5° to 50° C) Relative Humidity 10% to 80% Maximum Wet Bulb Temperature 84° F (29° C)		

### HP 9.5mm Desktop G2 Slim DVD-ROM Drive

Height	9.5 mm height	
Orientation	Either horizontal or vertical	
Interface type	SATA/ATAPI	
Disc recording capacity	Up to 8.5 GB DL or 4.7 GB standard	
Dimensions (W x H x D)	5.04 x 0.37 x 5.0 in (128 x 9.5 x 127 mm) without bezel	
Weight (max)	0.31 lb (140 g)	
Read Speeds	DVD-R DL DVD+R DVD+RW DVD+R DL DVD-R DVD-RW CD-R	Up to 6X Up to 8X Up to 8X Up to 6X Up to 8X Up to 6X Up to 24X



## Technical Specifications – Optical Drives

	CD-RWUp to 10XDVD-RW, DVD+RWUp to 8XDVD-R DL, DVD+R DLUp to 8XDVD+R, DVD-RUp to 8XDVD-ROM DL, DVD-ROMUp to 8XCD-ROM, CD-RUp to 24XCD-RWUp to 24X	
Access time (typical reads, including settling)	Random DVD-ROM: 170 ms (typical), CD-ROM: 170 ms (typical) Full Stroke DVD-ROM: 320 ms (typical), CD-ROM: 320 ms (typical) Stop Time 6 seconds (typical)	
Power	Source Slimline SATA DC power receptacle DC Power Requirement 5 VDC ± 5%-100 mV ripple p-p DC Current 5 VDC (< 1000 mA typical, 1600 mA maximum)	
Environmental conditions (operating - non-condensing)	Temperature 41° to 122° F (5° to 50° C) Relative Humidity 10% to 80% Maximum Wet Bulb Temperature 84° F (29° C)	



## Technical Specifications – Networking

### NETWORKING

10/100/1000 NIC	Ethernet Features	10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14)
		100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30) 1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40)
		Auto-Negotiation (Automatic Speed Selection)
		Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100 Mbit/s
	Power	ACPI compliant – multiple power modes
	Management	Situation-sensitive features reduce power consumption
		Advanced link down power saving for reducing link down power consumption
	Performance	TCP/IP/UDP Checksum Offload (configurable)
	Features	Protocol Offload (ARP & NS)
		Large send offload and Giant send offload
		Receiving Side Scaling
		Jumbo Frame 9K
	Manageability	Wake-on-LAN from standby and hibernation (Magic Packet and Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet only)
		PXE 2.1 Remote Boot
		Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause
		30)
		Comprehensive diagnostic and configuration software suite
		Virtual Cable Doctor for Ethernet cable status
	Interface	PCIe + SMBus
	NIC Device Driver Name	PCIe GBE Ethernet Family Controller

## Realtek 802.11ac (1x1) Wi-Fi® and Bluetooth® 4.2 Combo \*

Wireless LAN Standards <sup>1</sup>	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac 1. Wireless access point and Internet service required and not included. Availability of public wireless access points limited.		
Interoperability	Wi-Fi® certified modules		
Frequency Bands	802.11b/g/n	2.402 – 2.482 GHz <b>NOTE:</b> The FCC has declared products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 & 15.249 or otherwise disable those channels.	
	802.11a/n	4.9 – 4.95 GHz (Japan) 5.15 – 5.25 GHz 5.25 – 5.35 GHz 5.47 – 5.725 GHz 5.825 – 5.850 GHz	



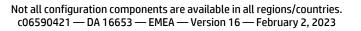
## Technical Specifications – Networking

Data Rates	802.11b: 1, 2, 5.5, 11 Mbps 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) 802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, and 80MHz)
Modulation	Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
Security <sup>2</sup>	IEEE and 64 / 128 bit WEP encryption for a/b/g mode only AES-CCMP: 128 bit in hardware 802.1x authentication WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. WPA2 certification IEEE 802.11i Cisco Certified Extensions, all versions through CCX4 and CCX Lite WAPI
	2 Check latest software/driver release for updates on supported security features.
Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)
Roaming	IEEE 802.11 compliant roaming between access points
Output Power <sup>3</sup>	802.11b : +14dBm minimum 802.11g : +12dBm minimum 802.11a : +12dBm minimum 802.11n HT20(2.4GHz) : +12dBm minimum 802.11n HT40(2.4GHz) : +12dBm minimum 802.11n HT20(5GHz) : +10dBm minimum 802.11n HT40(5GHz) : +10dBm minimum 802.11ac VHT80(5GHz) : +10dBm minimum 3. Maximum output power may vary by country according to local regulations.
Power Consumption	•Transmit mode2.0 W •Receive mode1.6 W •Idle mode (PSP)180 mW(WLAN Associated) •Idle mode50 mW(WLAN unassociated) •Connected Standby 10mW •Radio disabled8 mW
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode

(III)

## Technical Specifications – Networking

Receiver Sensitivity <sup>4</sup>	802.11b, 1Mbps : -93.5dBm maximum	802.11b, 1Mbps : -93.5dBm maximum		
	802.11b, 11Mbps : -84dBm maximum			
	802.11a/g, 6Mbps : -86dBm maximum			
	802.11a/g, 54Mbps : -72dBm maximum			
	802.11n, MCS07 : -67dBm maximum			
	802.11n, MCS07 : -67dBm maximum 802.11n, MCS15 : -64dBm maximum			
	802.11ac, MCS0 : -84dBm maximum			
	802.11ac, MCS9 : -59dBm maximum			
	4 Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).			
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth® communications			
Form Factors	PCI-Express M.2 MiniCard			
Dimensions	Type 2230 : 2.3 x 22.0 x 30.0 mm			
Weight	Туре 2230 : 2.8g			
Operating Voltage	3.3v +/- 9%			
Temperature	Operating:         14° to 158° F (-10° to 70° C)           Non-operating:         -40° to 176° F (-40° to 80° C)			
Humidity	Operating:10% to 90% (non-condensing)Non-operating:5% to 95% (non-condensing)			
Altitude	Operating:         0 to 10,000 ft (3,048 m)           Non-operating:         0 to 50,000 ft (15,240 m)			
LED Activity	LED Amber – Radio OFF; LED White – Radio ON			
HP Integrated Module with Blue	ooth 4.0/4.1/4.2 Wireless Technology			
Bluetooth <sup>®</sup> Specification	4.0/4.1/4.2 Compliant			
Frequency Band	2402 to 2480 MHz			
Number of Available Channels	Legacy : 0~79 (1 MHz/CH) BLE : 0~39 (2 MHz/CH)			
Data Rates and Throughput	Legacy : 3 Mbps data rate; throughput up to 2.17 Mbps			
	BLE : 1 Mbps data rate; throughput up to 0.2 Mbps Legacy : Synchronous Connection Oriented links up to 3, 64 kbps, voice channels			
	Legacy : Asynchronous Connection Less l 864 kbps symmetric (3-EV5)	inks 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or		
Transmit Power	The Bluetooth <sup>®</sup> component shall operate transmit power of + 4 dBm for BR and ED	e as a Class II Bluetooth® device with a maximum R.		



## Technical Specifications – Networking

Receiver Sensitivity Legacy		
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW	
Range	Legacy : 0~79 (1 MHz/CH) BLE : 0~39 (2 MHz/CH)	
Electrical Interface	USB 2.0 compliant	
Bluetooth <sup>®</sup> Software Supported Link Topology	Microsoft Windows Bluetooth <sup>®</sup> Software	
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark	
Certifications Bluetooth® Profiles Supported	FCC (47 CFR) Part 15C, Section 15.247 & 15.249	
Power Management Certifications	Microsoft Windows ACPI, and USB Bus Support	
Certifications Bluetooth <sup>®</sup> Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)	

Technical Specifications - Audio

### **HIGH DEFINITION AUDIO**

הר 230 טא מוונו טנטשפו רנ	HP	290	G4	<b>Microtower PC</b>
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Туре	Integrated
HD Stereo Codec	Realtek ALC3601 / ALC3867
Audio I/O Ports	Front side Combo jack for supporting CTIA, Rear side Line-in/ Line-out/ Mic-in jacks
Internal Speaker Amplifier	2W class D mono amplifier for the internal speaker only. External speakers must be powered externally.
Multi-streaming Capable	Playback multi-streaming can be enabled in the audio control panel to allow independent audio streams to be sent to/from the front and rear jacks or integrated speaker.
HD Audio Codec	Realtek ALC3601
Sampling	Independent sampling rates for DAC's and ADC's; supports resolutions from 16 to 24-bit; 44.1K/ 48 K/96K / 192K Hz for DAC and 44.1K/ 48K/ 96K/ 192K Hz Hz for ADC
Wavetable Syntheses	Yes
Analog Audio	Yes
# of Channels on Line-Out	Stereo
Internal Speaker	Yes
External Speaker Jack	2W class D mono amplifier for the internal speaker only. External speakers must be powered externally.
NOTE: Ontingel	

NOTE\*: Optional



Technical Specifications - Power

### **POWER SUPPLY**

Operating Voltage Range	90 – 264 VAC
Rated Voltage Range	100-240V AC
<b>Rated Line Frequency</b>	50/60 HZ
<b>Operating Line Frequency</b>	47 – 63 Hz
Rated Input Current	180W : <2.3A; 310W: <4A 500W: <6A
Rated Input Current with Energy Efficient* Power Supply	180W active PFC 87/90/87% efficient at 20/50/100% load (115V) 88/92/88% efficient at 20/50/100% load (230V); 310W active PFC 87/90/87% efficient at 20/50/100% load (115V) 88/92/88% efficient at 20/50/100% load (230V) 500W active PFC 87/90/87% efficient at 20/50/100% load (115V) 88/92/88% efficient at 20/50/100% load (230V)
DC Output	+12.1V
Current Leakage (NFPA 99: 2102)	Less than 500 microamps of leakage current at 120 Vac with the ground wire disconnected, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1. Less than 100 microamps of leakage current at 120 Vac with the ground wire intact with normal polarity, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1.
Power Supply Fan	180W/310W: 70*25mm (linear type) 500W: 70*25mm (PWM type)

Technical Specifications – Weights and Dimensions

### WEIGHT AND DIMENSIONS

Chassis (W x D x H)	6.12 x 11.93 x 13.28 in (155 x 303 x 337 mm) (w/ bezel)
System Volume	15.1 L
System Weight*	10.4 lbs / 4.7 kg
Packaged (H × W × D)	11.3 x 15.75 x 19.65 in 287 x 400 x 499 mm
Shipping Weight	17.64lb / 8 kg
Palletization Profile	6 units per layer 7layer max 42 per pallet Footprint -85.31x39.37x47.24 in (2167 x 1000 x1200 mm)

After-Market Options (availability may vary by region)

## **AFTERMARKET OPTIONS**

Туре	Description	Part #
Memory	HP 4GB DDR4-2666 DIMM	3TK85AA
	HP 8GB DDR4-2666 DIMM	3TK87AA
	HP 16GB DDR4-2666 DIMM	ЗТК8ЗАА
Storage	HP 500GB SATA 6.0Gb/s Hard Drive	QK554AA
	HP 1TB 7200rpm SATA 6Gbps Hard Drive	QK555AA
	HP PCIe NVME TLC 256GB SSD M.2 Drive	1CA51AA
	HP 256GB SATA TLC Non-SED Solid State Drive	P1N68AA
	HP 9.5mm G3 8/6/4 SFF G4 400 SFF/MT DVD Writer	1CA53AA
Graphics	NVIDIA <sup>®</sup> GT 730 2GB DP Card	Z9H51AA
	AMD Radeon™ R7 430 2GB 2DP Card	5JW82AA
Security	HP Business PC Security Lock V3 Kit	3XJ17AA
	HP Keyed Cable Lock 10mm kit	T1A62AA
Adapters	HP HDMI Standard Cable Kit	
Audpleis	HP USB to Serial Port Adapter	J7B60AA
	HP PCIe x1 Parallel Port Card	
Notworking		Γονογάλ
Networking	Intel Ethernet I210-T1 GbE NIC Card	E0X95AA
Input	HP USB Mouse	QY777AA
	HP USB Hardened Mouse	P1N77AA
	HP USB Grey v2 Mouse	Z9H74AA
	HP USB Keyboard	QY776AA
	HP PS/2 Business Slim Keyboard	N3R86AA
	HP USB Business Slim Keyboard	N3R87AA
	HP Backlit USB Mechanical Keyboard	4RV35AA
	HP USB Antimicrobial Slim Keyboard and Mouse	Z9H50AA
Others	HP Business Headset v2	
	HP S101 Speaker bar	5UU40AA

## Change Log

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Date of change:	Version History:	Change	Description of change:
June 4, 2020	From v1 to v2	Remove	Nvidia GeForce GT730 2GB Card from Graphics section
June 5, 2020	From V2 to V3	Added	Disclaimer #4 in rear call outs section
July 21, 2020	From V3 to V4	Added	Environmental section
July 24, 2020	From V4 to V5	Added	Intel Celeron G5905
July 29, 2020	From V5 to V6	Correction	Dimensions order
September 24, 2020	From V6 to V7	Addition	Xerox <sup>®</sup> DocuShare <sup>®</sup> and footnote to software section.
November 2, 2020	From V7 to V8	Addition	Disclaimer an update to 🛛 I7-10700 information in processors section
March 3, 2021	From V8 to V9	Update	Environmental specs updated
June 23, 2021	From V9 to V10	Addition	ALC3867-CG added to Audio specs
August 31, 2021	From V10 to V11	Removal	Footnote from rearview call outs image
September 23, 2021	From V11 to V12	Update	EPEAT disclaimer
October 18, 2021	From v12 to v13	Addition	G6405, G6605 and Core i3-10105 processors added
October 29, 2021	From v13 to v14	Update	OS section
June 15, 2022	From v14 to v15	Update	Intel <sup>®</sup> Core™ i5 processors / Environmental table certifications updated
February 2, 2023	From v15 to v16	Update	i3-10100 updated to 4.3GHz at Processors section

# tehnotzka

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